

## Photo Diode

### ■FEATURES

- Leadless surface mount type: 2.1 X 2.6 X 0.8mm
- Sensitive peak wavelength: 900nm
- Corresponding to infrared light from the blue-violet light
- Active area: 1.5mm X 1.5mm
- Pb free solder re-flowing permitted: 260°C, 2times
- Pb free, Halogen free
- Conformity to RoHS directive

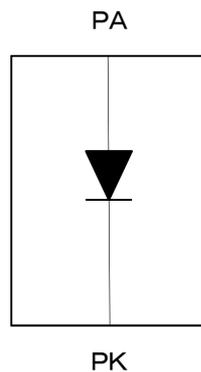
### ■GENERAL DESCRIPTION

The NJL6414R is the photodiode sensor capable of detecting light in a wide wavelength range of up to infrared light from the blue-violet light. A thin and small package of COBP is adopted, and providing high efficient space-saving.

### ■APPLICATION

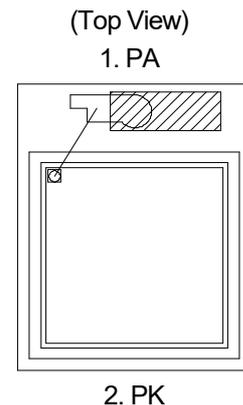
- Heart rate monitoring of Wearable Devices (In-Ear phone, Smart watch, Fitness Tracker etc.)
- Mobile Devices
- Optical smoke detector (Dual sensing of blue and IR light)

### ■BLOCK DIAGRAM



### ■PIN CONFIGURATION

PIN NO.	SYMBOL	DESCRIPTION
1	PA	Anode
2	PK	Cathode



### ■ORDERING INFORMATION

PART NUMBER	PACKAGE OUTLINE	RoHS	HALOGEN-FREE	TERMINAL FINISH	MARKING	WEIGHT (mg)	MOQ(pcs)
NJL6414R	COBP	✓	✓	Au	No marking	8.97	3,000

## ■ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATINGS	UNIT
Reverse Voltage	$V_R$	35	V
Operating Temperature Range	$T_{opr}$	-30 to +85	°C
Storage Temperature Range	$T_{stg}$	-40 to +100	°C
Reflow Soldering Temperature	$T_{sol}$	260	°C

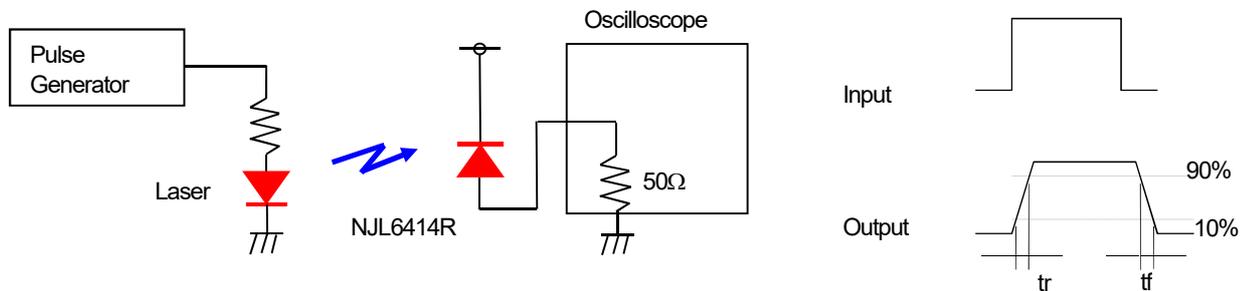
## ■ELECTRICAL CHARACTERISTICS ( $T_a=25\text{ }^\circ\text{C}$ )

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Dark Current	$I_D$	$V_R=10V$	—	0.5	5.0	nA
Forward Voltage	$V_F$	$I_F=1mA$	—	0.6	1.0	V
Capacitance	$C_t$	$V_R=0V, f=1MHz$	—	30	—	pF
		$V_R=2.5V, f=1MHz$	—	10	—	pF
		$V_R=20V, f=1MHz$	—	5	—	pF
Peak Wavelength	$\lambda_P$	$V_R=0V$	—	900	—	nm
Sensitivity	S	$V_R=2.5V, \lambda=405nm$ *1	0.21	0.27	—	AW
		$V_R=2.5V, \lambda=780nm$	—	0.47	—	AW
Rise time	$t_r$	$V_R=2.5V, R_L=50\Omega, 10-90\%$ , $\lambda=405nm$ *1	—	16	—	ns
Fall time	$t_f$	$V_R=2.5V, R_L=50\Omega, 10-90\%$ , $\lambda=405nm$ *1	—	22	—	ns

※In the Electro-Optical characteristics table, items that are showed only the typical value are not tested in manufacturing process.

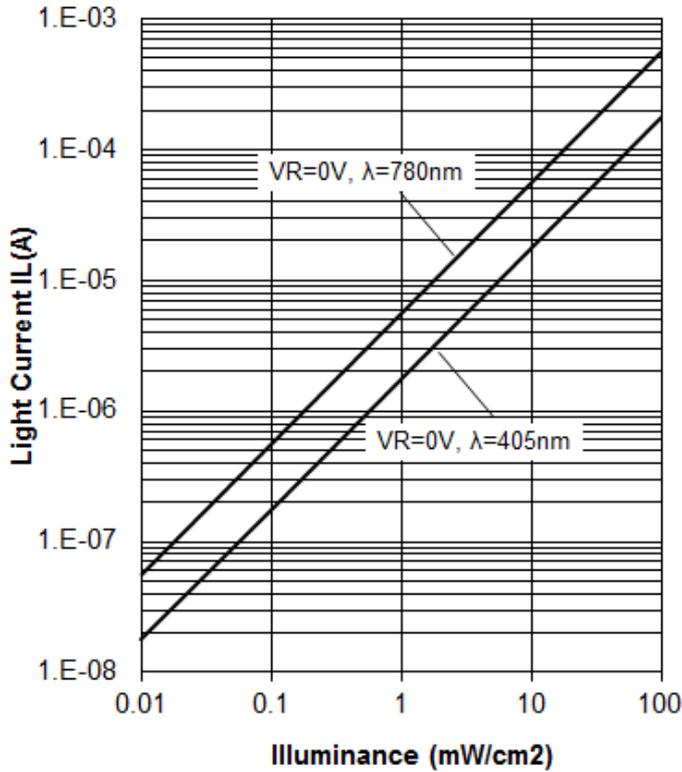
\*1 : If it use for around  $\lambda=405nm$ , there is limitation for usage. Please be careful when using.

## ■RESPONSE( $t_r/t_f$ ) TEST CONDITION

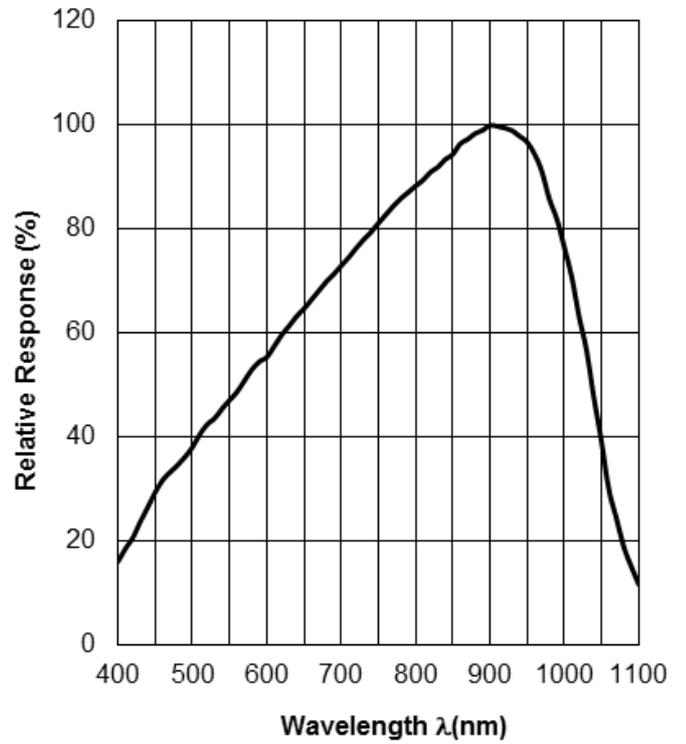


## ■ TYPICAL CHARACTERISTICS

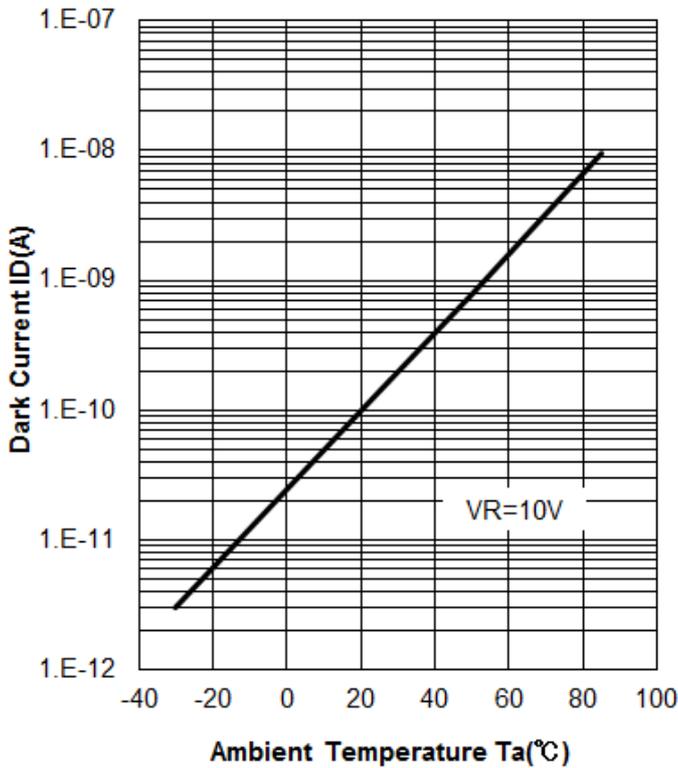
Light Current vs. Illuminance (Ta=25°C)



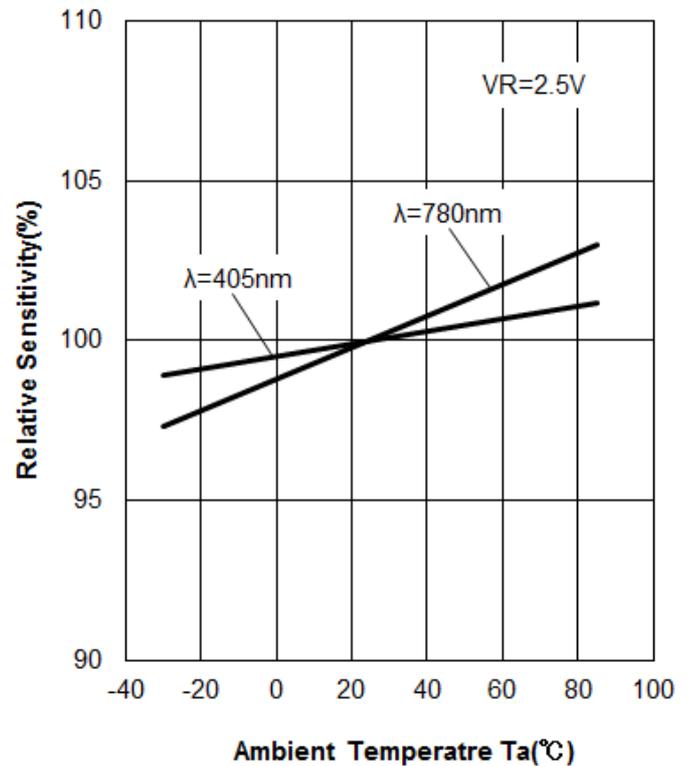
Spectral Response (Ta=25°C)



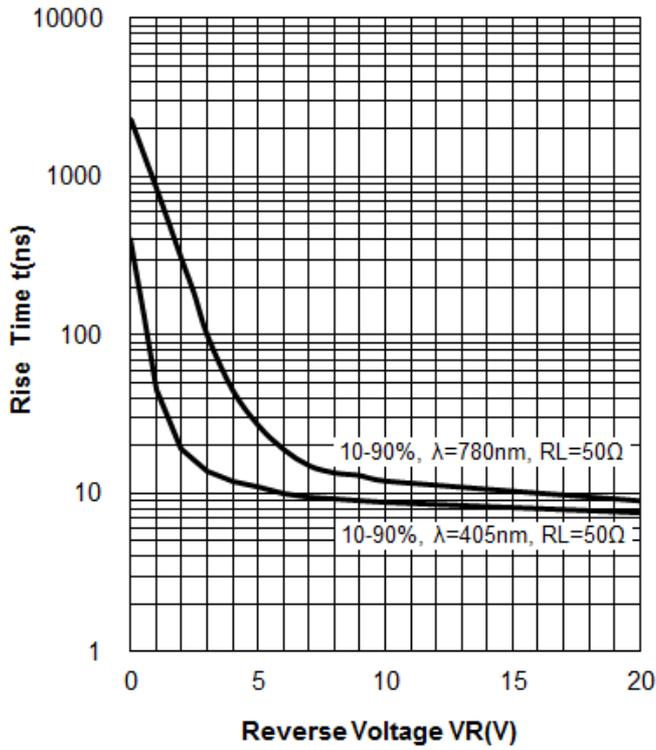
Dark Current vs. Temperature



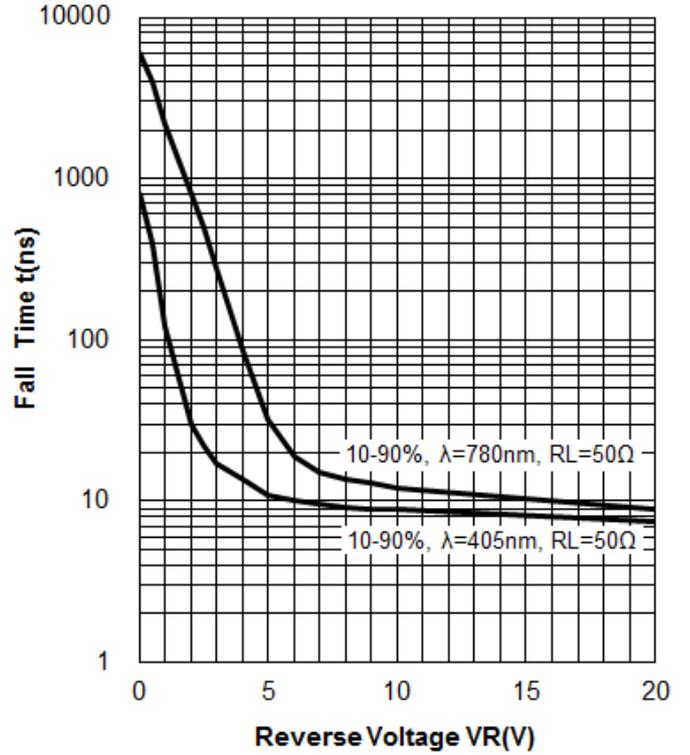
Relative Sensitivity vs. Temperature



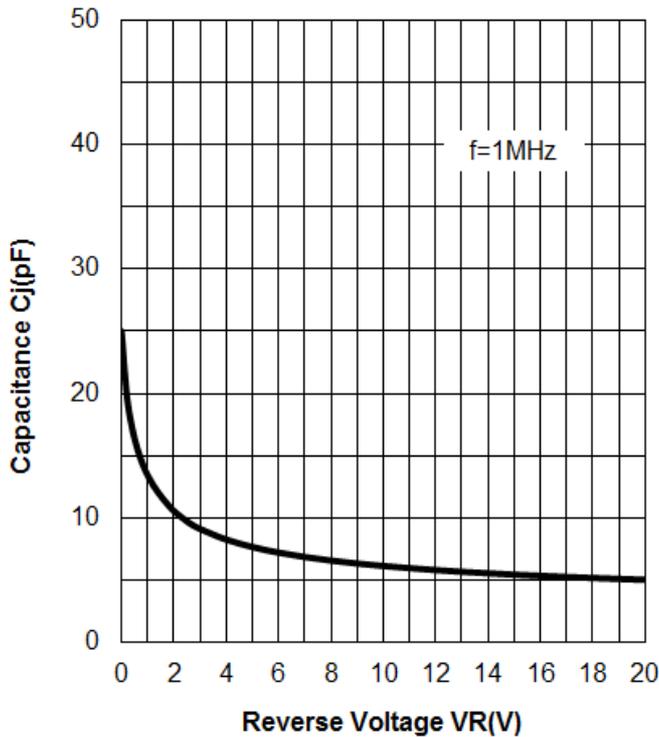
Rise time vs. Reverse Voltage (Ta=25°C)



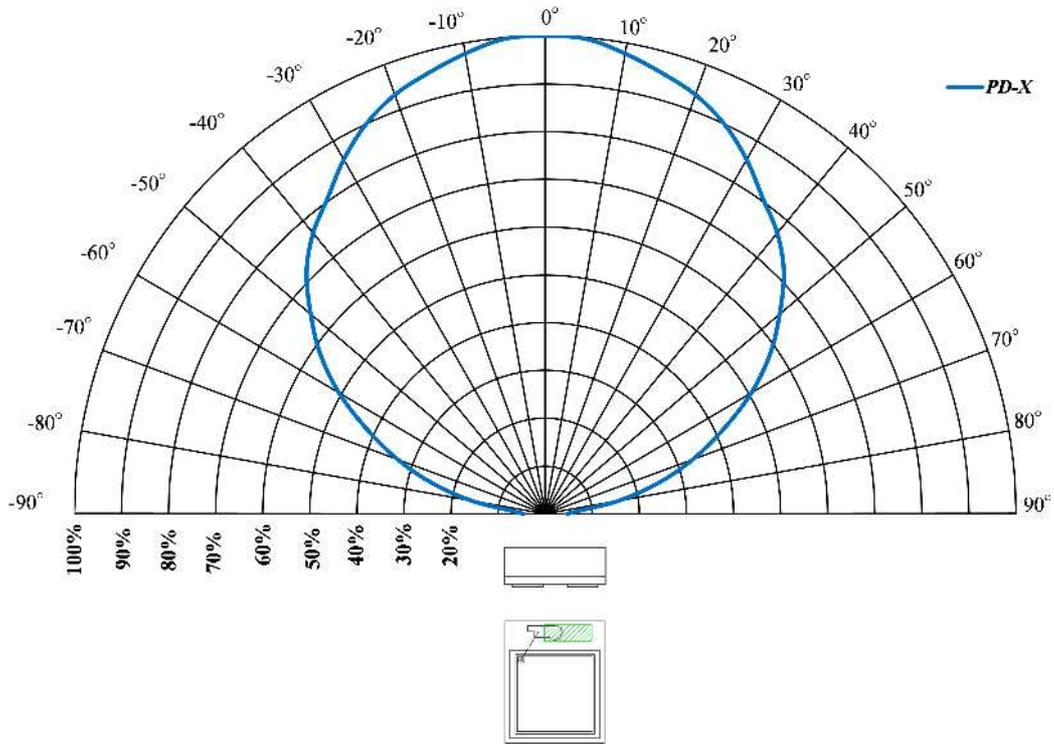
Fall time vs. Reverse Voltage (Ta=25°C)



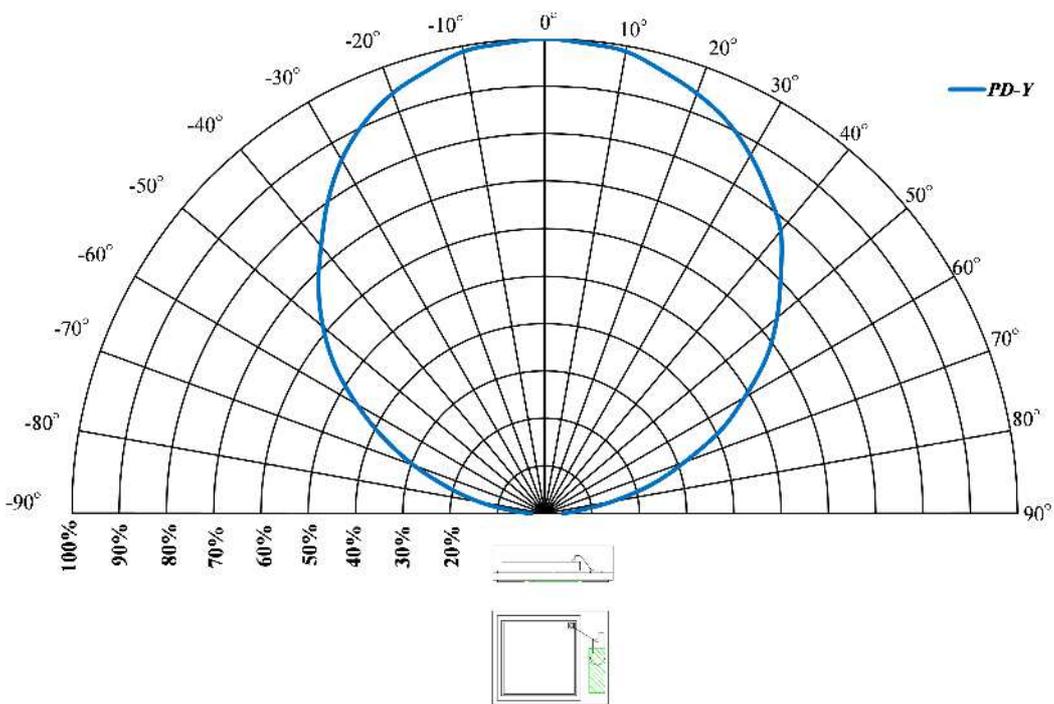
Capacitance vs. Reverse Voltage (Ta=25°C)



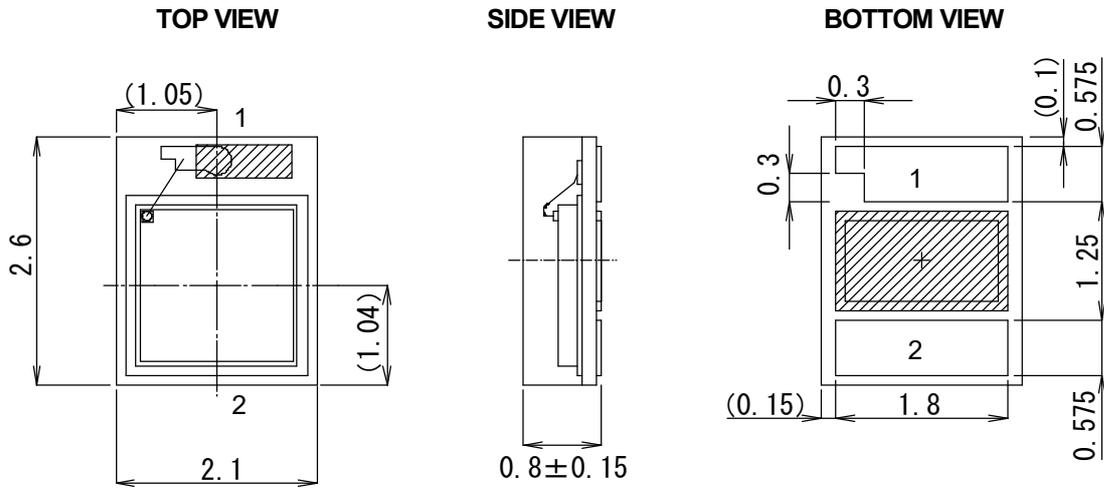
### Directivity at Package direction X



### Directivity at Package direction Y



## ■PACKAGE OUTLINE

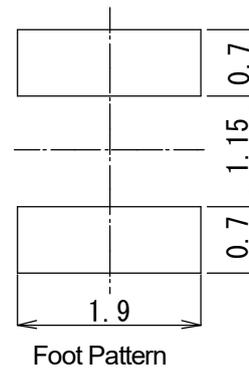


1: PA

2: PK

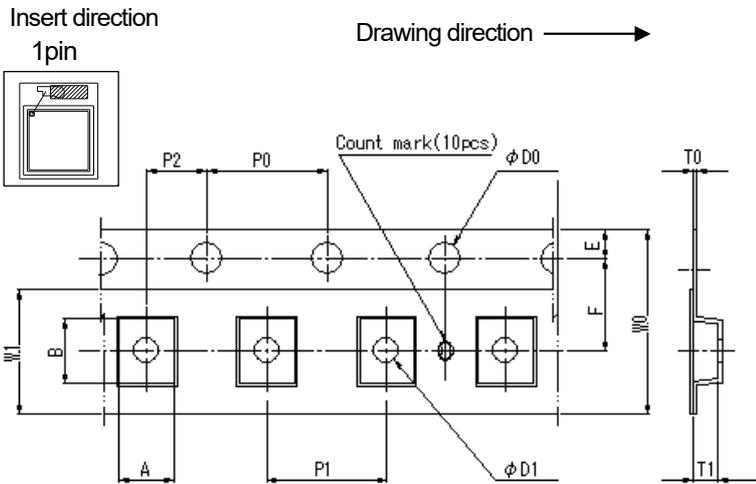
Unspecified tolerance :  $\pm 0.1\text{mm}$

Dimensions in parenthesis are shown for reference.



## PACKING SPECIFICATION

PACKING DIMENSIONS UNIT : mm



SYMBOL	DIMENSION	REMARKS
A	2.40±0.05	BOTTOM DIMENSION
B	2.90±0.05	BOTTOM DIMENSION
D0	φ1.50 <sup>+0.1/-0</sup>	
D1	φ1.05±0.05	
E	1.75±0.10	
F	3.50±0.10	
P0	4.00±0.10	
P1	4.00±0.10	
P2	2.00±0.05	
T0	0.20±0.05	
T1	1.10±0.05	
W0	8.0 <sup>+0.3/-0.1</sup>	
W1	5.40±0.10	THICKNESS 0.1MAX

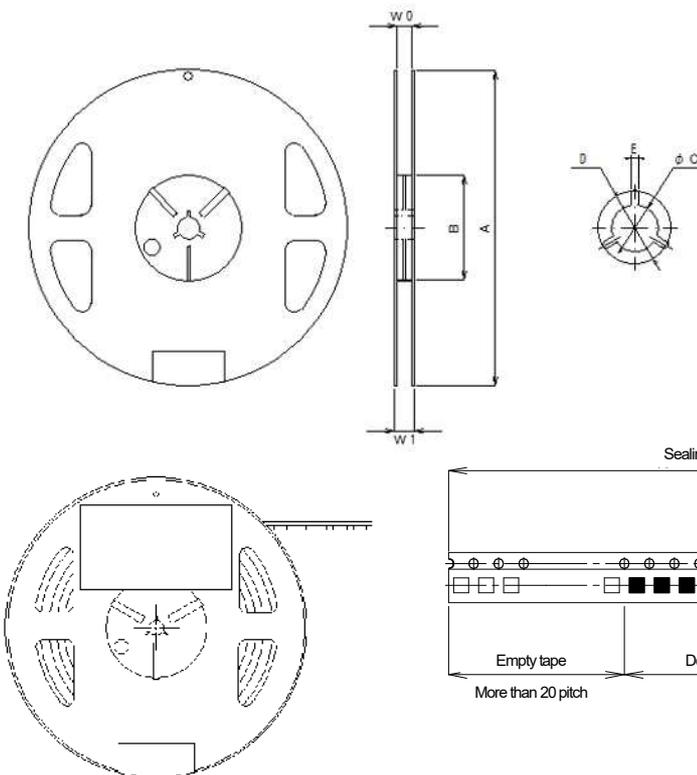
Carrier tape material : Polycarbonate(antistatic)  
Cover tape material : PET(antistatic)

## Taping Strength

There is a peel strength in the range of 0.2 to 0.7N when was peeled at a rate of 300mm per minute in opening angle 165 to 180° between the carrier tape and the cover tape.

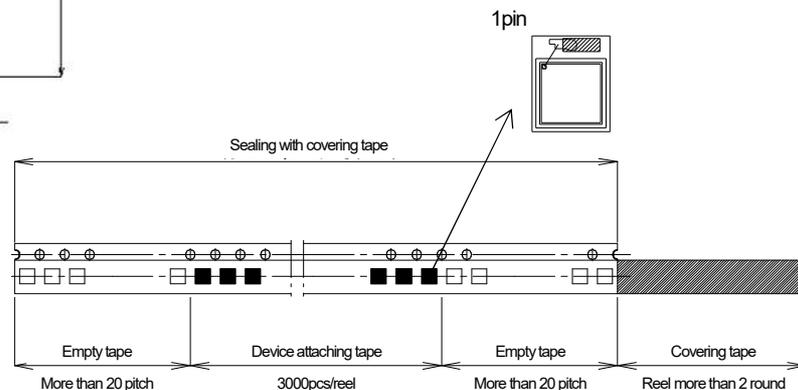
## Packaging

- The taped products are to be rolled up on the taping reel as on the drawing.
- Rolling up specification
  - Start rolling : Carrier tape open space more than 20 Pieces.
  - End of rolling : Carrier tape open space more than 20 Pieces, and 2 round of reel space at the cover tape only.
- Taping quantity : 3,000 Pieces
- Seal off after putting each reels in a damp proof bag with silica gel.



SYMBOL	DIMENSION	REMARKS
A	φ180.0±1.0	
B	φ60.0±1.0	
C	φ13.0±0.2	
D	φ21.0±0.8	
E	2.0±0.5	
W0	9.0±0.3	INNER DIMENSION
W1	11.4±1.0	OUTER DIMENSION

Reel material : PS(antistatic)



## RECOMMENDED MOUNTING METHOD

### NOTE

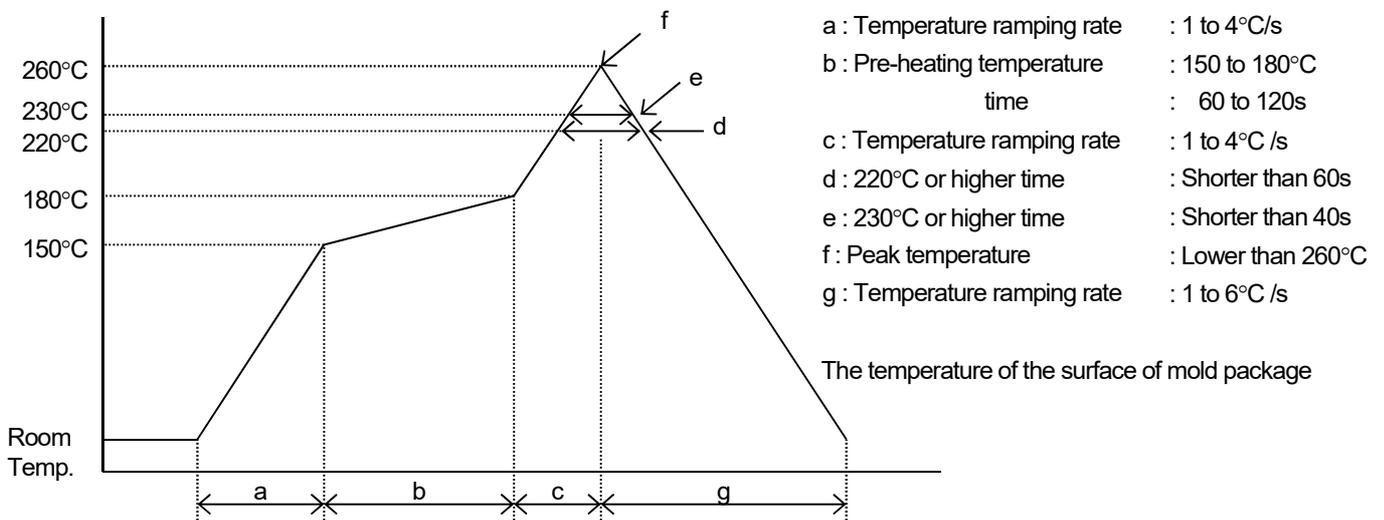
Mounting was evaluated with the following profiles in our company, so there was no problem.  
However, confirm mounting by the condition of your company beforehand.

The exposure of device under higher temperature many affect to the reliability of the products, it is recommended to complete soldering in the shortest time possible.

Mounting: Two Times soldering is allowed.

## INFRARED REFLOW SOLDERING METHOD

### Recommended reflow soldering procedure



(NOTE1) Using reflow furnace with short wave infrared radiation heater such as halogen lamp

Regarding temperature profile, please refer to those of reflow furnace.

In this case the resin surface temperature may become higher than lead terminals due to endothermic ally of black colored mold resin. Therefore, please avoid from direct exposure to mold resin.

(NOTE2) Other method

Such other methods of soldering as dipping the device into melted solder and vapor phase method (VPS) are not appropriate because the body of device will be heated rapidly. Therefore, these are not recommended to apply.

(NOTE3) The resin gets softened right after soldering, so, the following care has to be taken

Not to contact the lens surface to anything.

Not to dip the device into water or any solvents.

## FLOE SOLDERING METHOD

Flow soldering is not possible.

## IRON SOLDERING METHOD

Iron soldering is not possible.

**■ CLEANING**

Avoid washing the device after soldering by reflow method.

**■ IC STORAGE CONDITIONS AND ITS DURATION****(1) Temperature and humidity ranges**

Pack Sealing	Temperature:	5 to 40 [°C]
	Humidity:	40 to 80 [%]
Pack Opening	Temperature:	5 to 30 [°C]
	Humidity:	40 to 70 [%]

After opening the bag, solder products within 48h.

Avoid a dry environment below 40% because the products are easily damageable by the electrical discharge.

Store the products in the place where it does not create dew with the products due to a sudden change in temperature.

(2) When baking, place the reel vertically to avoid load to the side.

(3) Do not store the devices in corrosive-gas atmosphere.

(4) Do not store the devices in a dusty place.

(5) Do not expose the devices to direct rays of the sun.

(6) Do not allow external forces or loads to be applied to IC's.

(7) Be careful because affixed label on the reel might be peeled off when baking.

(8) The product is recommended to do the baking before using for the stability of the quality.

**■ BAKING**

In case of keeping expect above condition be sure to apply baking.

Baking method: Ta=60°C, 48 to 72h, one time baking is allowed

**■ STORAGE DURATION**

Within a year after delivering this device.

For the products stored longer than a year, confirm their terminals and solder ability before they are used.

**■ APPLICATION NOTES****(1) Attention in handling**

Treat not to touch the lens surface.

Avoid dust and any other foreign materials on the lens surface such as point, bonding material, etc.

When mounting, special care has to be taken on the mounting position and tilting of the device because it is very important to place the device to the optimum position to the object.

**(2) Attention in designing**

Avoid the entering ambient light into light receiving part for avoid the malfunction by ambient light. Furthermore, there is possibility of malfunction when there are the other mounted parts by near this product peripheral.

When using the laser diode in the vicinity of  $\lambda=405\text{nm}$ , there is the restriction in terms of use.

Please be careful in the case of the use.

**■ MOISTURE SENSITIVITY LEVELS**

JEDEC : Level 5

## [ CAUTION ]

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